

IN THE SPECIFICATION:

Kindly amend the specification as follows:

Page 1, immediately beneath the title, please insert the following new paragraph:

This application claims priority from Japanese Patent Application No. 2003-132646, filed May 12, 2003, the entire disclosure of which is incorporated herein by reference.

Page 1, please amend the paragraphs on page 1, line 20 to lines 25, as follows:

An assembly structure is used as the heat-resistant ceramic core (see ~~Patent Literature 1~~ the official publication of Japanese Patent No. 502159, 2003) to form a complicated hollow flow channel with the three-dimensional shape.

~~[Patent Literature 1]~~ The official publication of Japanese Patent No. 502159, 2003 is hereinafter referred to as Patent Literature 1.